



#### **General Description**

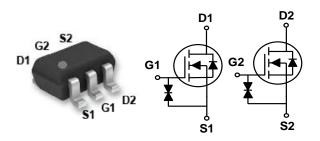
These dual N Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV <sub>DSS</sub>	R <sub>DS(ON)</sub>	Ι <sub>D</sub>
60 V	3 Ω	300 mA

#### **Features**

- 60V, 300mA,  $R_{DS(ON)}$ =3 $\Omega$ @ $V_{GS}$ =10V
- · Fast switching
- · Green Device Available
- · Suit for 2.5V Gate Drive Applications
- · G-S ESD Protection Diode Embedded

#### SOT-363 Pin Configuration



#### **Applications**

- Notebook
- · Load Switch
- Networking
- · Hand-Held Instruments

Symbol	Parameter	Rating	Unit
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> =25°C)	300	m/
	Drain Current - Continuous (T <sub>C</sub> =100°C)	240	m/
I <sub>DM</sub>	Drain Current - Pulsed (NOTE 1)	1.2	Α
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> =25°C)	275	m۷
' D	Power Dissipation - Derate above 25°C	2.2	mW/
$T_J$	Operating Junction Temperature Range	-50 to 150	°C
$T_{STG}$	Storage Temperature Range	-50 to 150	°C
Marking Code		L	

Thermal Characteristics						
Symbol	Parameter	Тур.	Max	Unit		
$R_{ heta JA}$	Thermal Resistance Junction to Ambient		450	°C/W		





### Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)

#### **Off Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0V , $I_D$ =250uA	60			V
I <sub>DSS</sub>	iDrain-Source Leakage Current	$V_{DS}$ =48V , $V_{GS}$ =0V , $T_J$ =25°C			1	uA
		$V_{DS}$ =48V , $V_{GS}$ =0V , $T_{J}$ =85 $^{\circ}$ C			10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ =±20V , $V_{DS}$ =0V			±20	uA

#### On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	$V_{GS}$ =10V , $I_D$ =0.3A		1.1	3	Ω
		$V_{GS}$ =4.5V , $I_D$ =0.2A		1.3	4	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250uA$	1.2	2.0	2.5	V

#### **Dynamic and switching Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
C <sub>iss</sub>	Input Capacitance			23	46	
C <sub>oss</sub>	Output Capacitance	$V_{ m DS}$ =30V , $V_{ m GS}$ =0V , F=1MHz		16	32	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			10	20	

#### **Drain-Source Diode Characteristics and Ratings**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			300	mA
I <sub>SM</sub>	Pulsed Source Current (NOTE 3)				600	mA
$V_{SD}$	Diode Forward Voltage (NOTE 3)	$V_{GS}$ =0V , $I_S$ =0.2A , $T_J$ =25 $^{\circ}$ C			1	V

#### NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The data tested by pulsed , pulse width  $\leq 300 \text{us}$  , duty cycle  $\leq 2\%$ .
- 3. Essentially independent of operating temperature.





#### **Characteristics Curves**

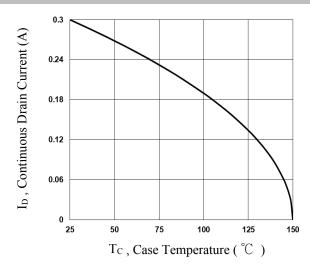


Fig.1 Continuous Drain Current vs. Tc

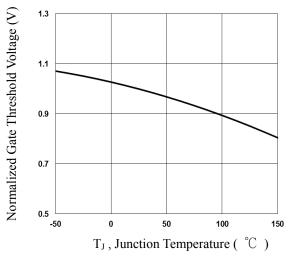


Fig.3 Normalized Vth vs. TJ

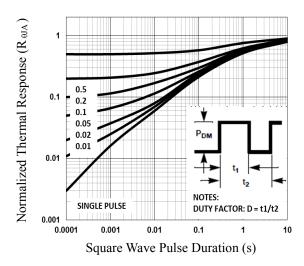


Fig.5 Normalized Transient Impedance

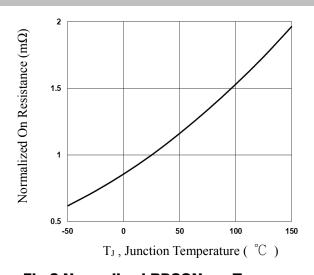
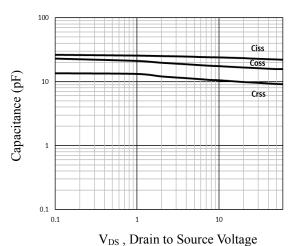


Fig.2 Normalized RDSON vs. TJ



· bs , Brain to source ver

Fig.4 Capacitance

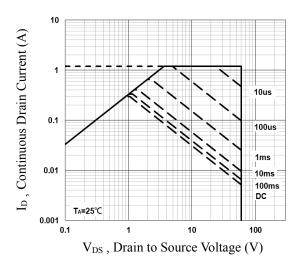
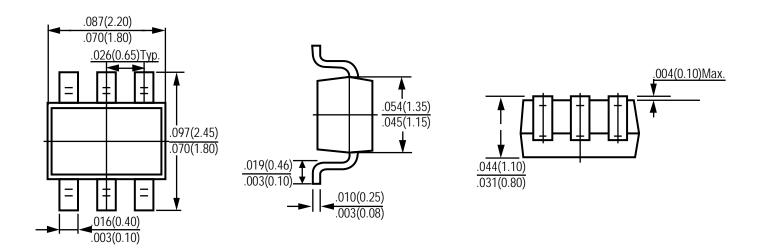


Fig.6 Maximum Safe Operation Area





### **Package Outline Dimensions**



**SOT-363**Dimensions in inches and (millimeters)





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